

1. Part No. Expression

W D 3 5 3 2 F 7 5 0 - R C - 1 0

(a) (b) (c) (d) (e)(f) (g)

(a) Series Code

(b) Dimension Code

(c) Material Code

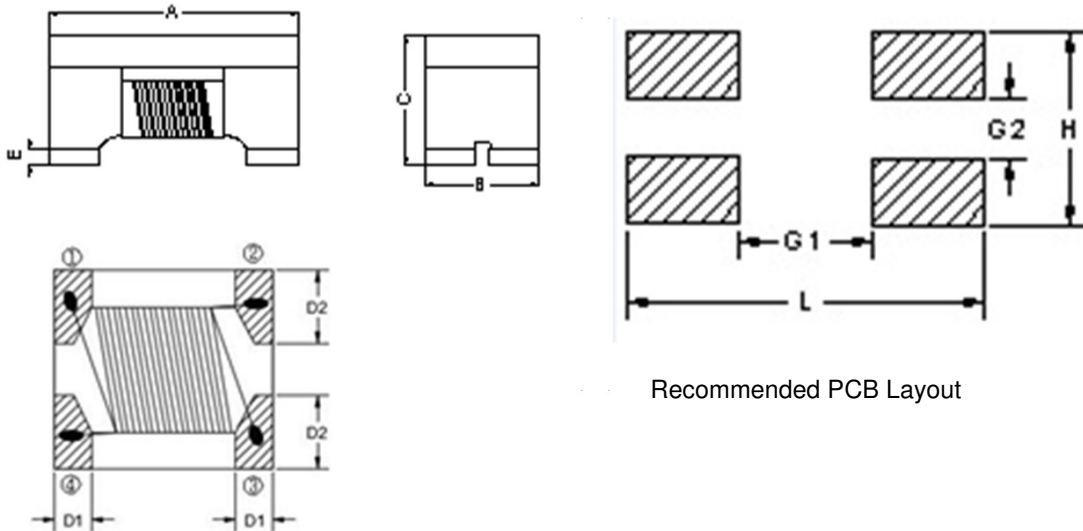
(d) Inductance Code

(e) Packaging Code

(f) Current Code

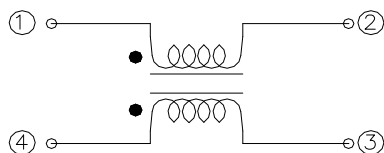
(g) Special Code

2. Configuration & Dimensions: (Unit:- mm)



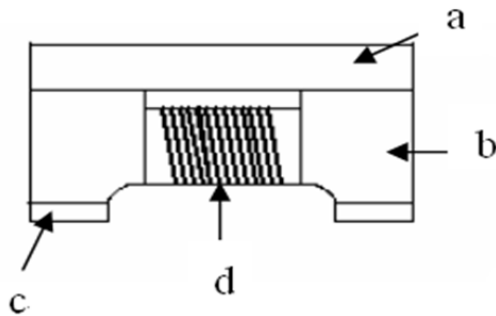
A	B	C	D1	D2	L	H	G1	G2
3.5±0.2	3.2±0.2	2.3±0.2	0.63±0.1	1.18±0.1	4.40 Ref	3.80 Ref	2.45 Ref	0.90 Ref

3. Schematic



NOTE: Specifications subject to change without notice. Please check our website for latest information.

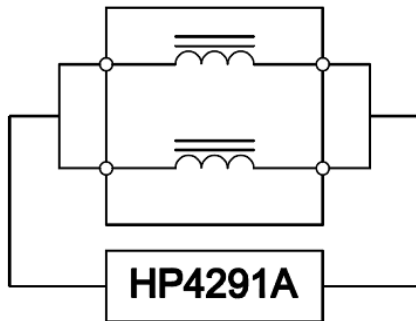
4. Material List



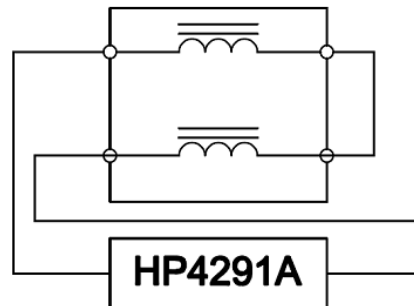
a)	Upper Plate
b)	Core
c)	Terminal
d)	Wire

5. Measuring Circuits 2 Lines

Common mode



Differential mode



6. General Specifications

- (a) Operating Temp. : -40°C to +85°C (Including self - temperature rise).
- (b) Storage Temp. : -40°C to +85°C (On board).
- (c) Irms: Based on temperature rise ΔT 40°C Max at rated current.
- (d) Storage Condition (Component in its packaging)
 - i) Temperature: Less than 40°C
 - ii) Humidity: 60% RH

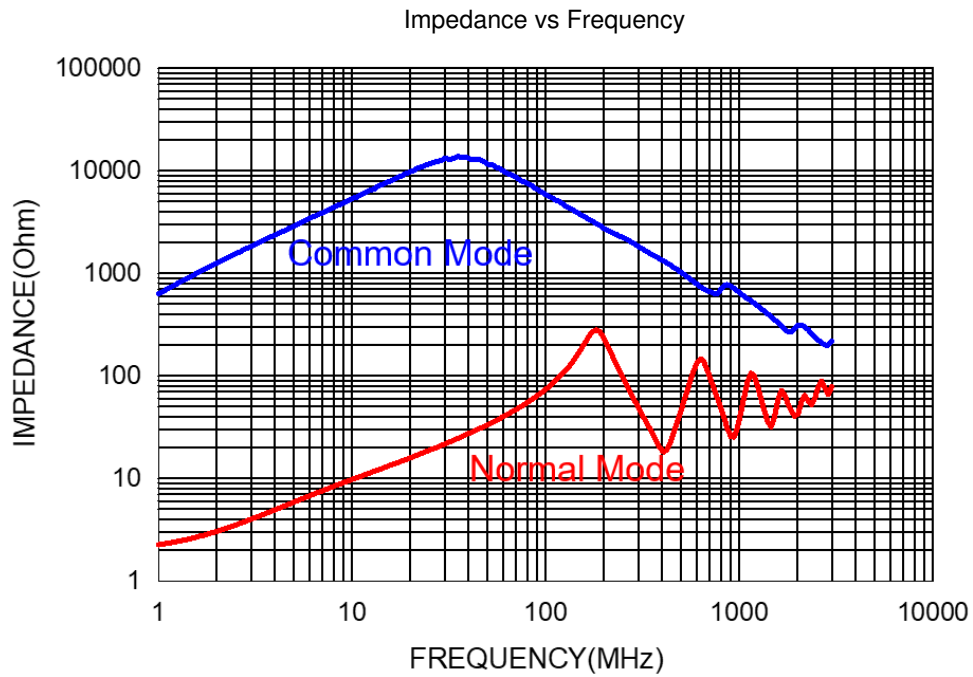
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7. Electrical Characteristics

Part Number	Inductance (uH) @0.1V/100kHz Min	DCR (Ω) Max	Rated Current (mA)	Rated Volt. (Vdc)	Withstand Volt. (Vdc) Max	IR (MΩ) Min
WD3532F750-RC-10	75	0.8	300	50	125	10

8. Characteristics Curve



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9. Soldering and Mounting

Mildly activated rosin fluxes are preferred. Our terminations are suitable for re-flow soldering systems. If hand soldering cannot be avoided, the preferred technique is the utilization of hot air soldering tools.

9-1 IR Soldering Reflow

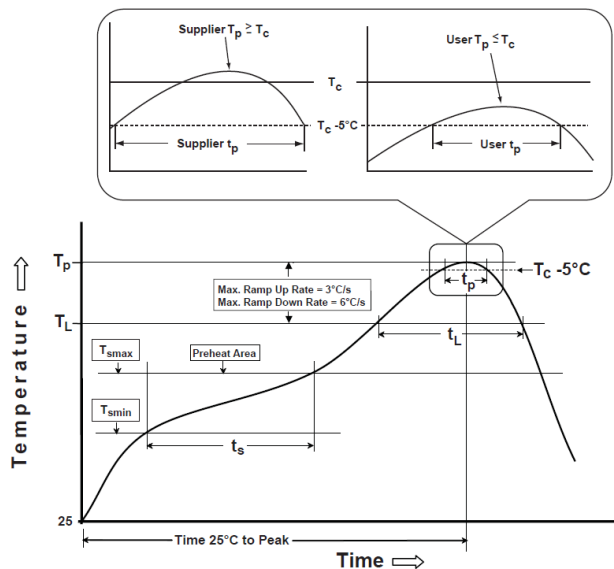
Recommended temperature profiles for lead free re-flow soldering in Figure 1, Table 1.1 & 1.2 (J-STD-020E).

9-2 Iron Reflow

Products attachment with a soldering iron is discouraged due to the inherent process control limitations. In the event that a soldering iron must be employed the following precautions are recommended (Figure 2).

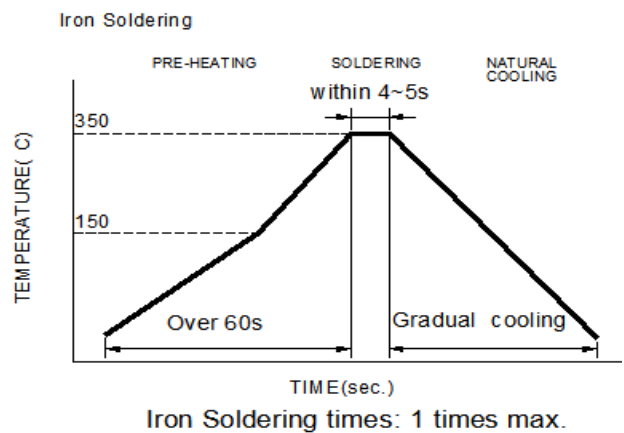
Note:

- a) Preheat circuit and products to 150°C.
- b) 355°C tip temperature (Max.)
- c) Never contact the ceramic with the iron tip
- d) 1.0mm tip diameter (Max.)
- e) Use a 20 watt soldering iron with tip diameter of 1.0mm
- f) Limit soldering time to 4~5 sec.



Reflow times: 3 times Max

Figure 1: IR Soldering Reflow



Soldering iron method: 350± 5°C Max

Figure 2: Iron soldering temperature profiles

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Table (1.1): Reflow Profiles

Profile Type:	Pb-Free Assembly
Preheat	
-Temperature Min (T_{smin})	150°C
-Temperature Max (T_{smax})	200°C
-Time (t_s) from (T_{smin} to T_{smax})	60-120seconds
Ramp-up rate (T_L to T_p)	3°C/second max.
Liquidus temperature (T_L)	217°C
Time (t_L) maintained above T_L	60-150 seconds
Classification temperature (T_c)	See Table (1.2)
Time (t_p) at $T_c - 5^\circ\text{C}$ (T_p should be equal to or less than T_c .)	< 30 seconds
Ramp-down rate (T_p to T_L)	6°C /second max.
Time 25°C to peak temperature	8 minutes max.

T_p: maximum peak package body temperature, **T_c**: the classification temperature.

For user (customer) **T_p** should be equal to or less than **T_c**.

Table (1.2) Package Thickness/Volume and Classification Temperature (T_c)

	Package Thickness	Volume mm ³ <350	Volume mm ³ 350-2000	Volume mm ³ >2000
PB-Free Assembly	<1.6mm	260°C	260°C	260°C
	1.6-2.5mm	260°C	250°C	245°C
	≥2.5mm	250°C	245°C	245°C

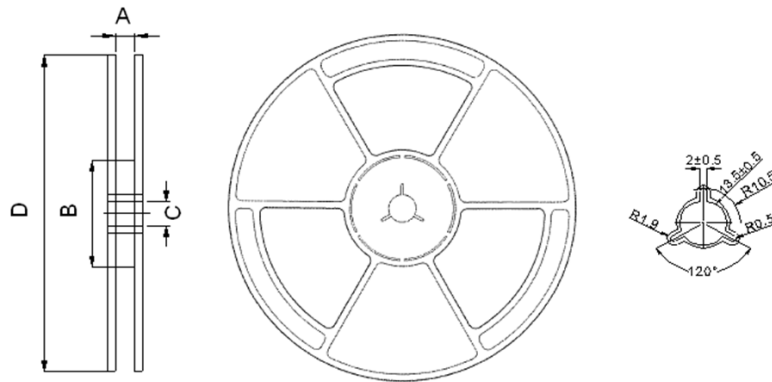
Reflow is referred to standard IPC/JEDEC J-STD-020E.

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10. Packaging Information

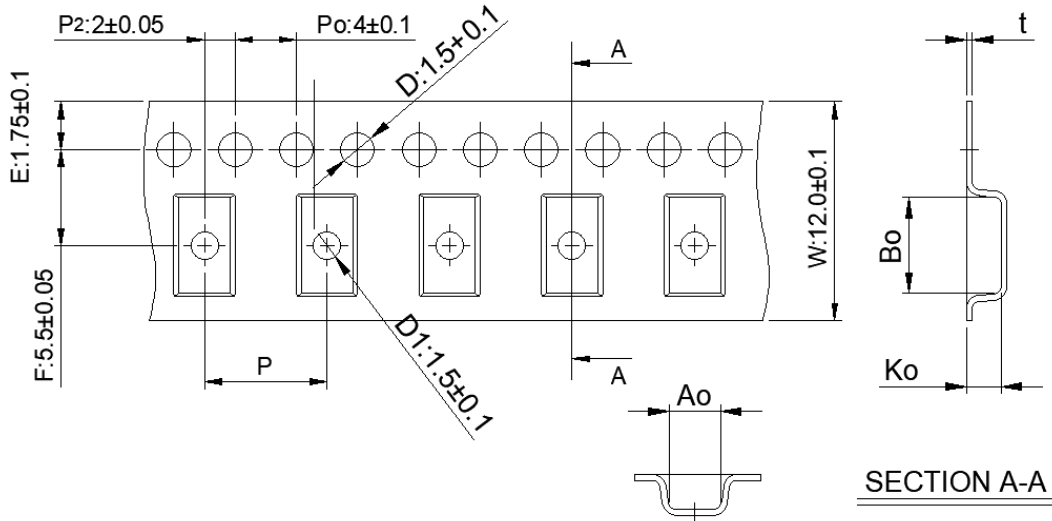
10-1 Reel Dimension



13 "x12mm

Type	A(mm)	B(mm)	C(mm)	D(mm)
13"x12mm	12±1.5	100±0.5	13.2±0.5	330±0.5

10-2 Tape Dimension / 12mm



Series	Bo(mm)	Ao(mm)	Ko(mm)	P(mm)	t(mm)
WD3532F	3.80±0.1	3.40±0.1	2.50±0.1	8.00±0.1	0.26±0.05

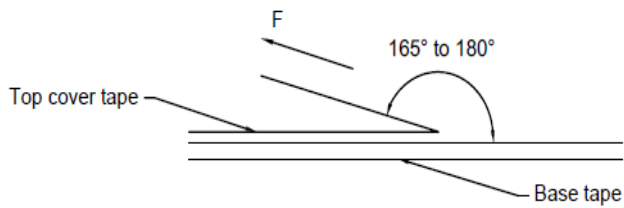
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10-3 Packaging Quantity

Chip Size	WD3532F
Chip / Reel	2000
Inner Box	4000
Carton	32000

10-4 Tearing Off Force



The force for tearing off cover tape is 15 to 80 grams in the arrow direction under the following conditions.

Room Temp. (°C)	Room Humidity (%)	Room atm (hPa)	Tearing Speed mm/min
5~35	45~85	860~1060	300

Application Notice:

1. Storage Conditions:

To maintain the solderability of terminal electrodes:

- a) Recommended products should be used within 12 months from the time of delivery.
- b) The packaging material should be kept where no chlorine or sulfur exists in the air.

2. Transportation:

- a) Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
- b) Vacuum pick up is strongly recommended for individual components.
- c) Bulk handling should ensure that abrasion and mechanical shock are minimized.

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